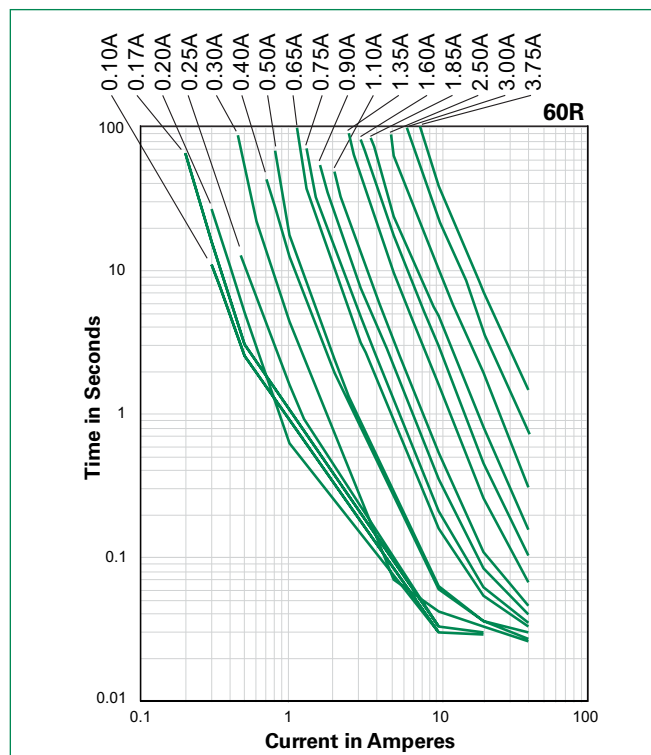


Temperature Derating

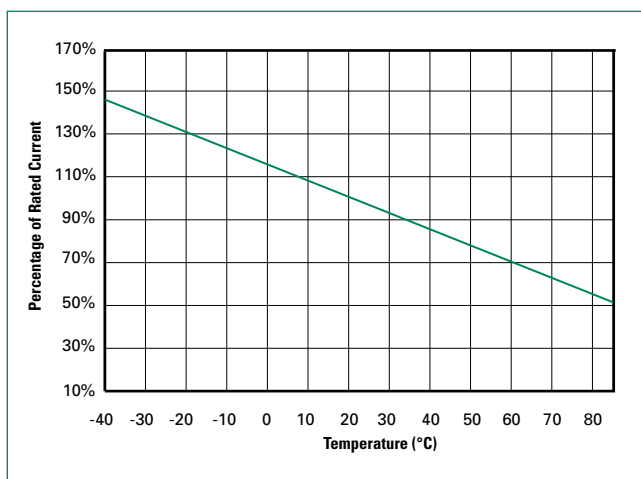
Part Number	Ambient Operation Temperature								
	-40°C	-20°C	0°C	20°C	40°C	50°C	60°C	70°C	85°C
Hold Current (A)									
60R010X	0.16	0.14	0.12	0.10	0.08	0.07	0.06	0.05	0.04
60R017X	0.26	0.23	0.20	0.17	0.14	0.12	0.11	0.09	0.07
60R020X	0.31	0.27	0.24	0.20	0.16	0.14	0.13	0.11	0.08
60R025X	0.39	0.34	0.30	0.25	0.20	0.18	0.16	0.14	0.10
60R030X	0.47	0.41	0.36	0.30	0.24	0.22	0.19	0.16	0.12
60R040X	0.62	0.54	0.48	0.40	0.32	0.29	0.25	0.22	0.16
60R050X	0.78	0.68	0.60	0.50	0.41	0.36	0.32	0.27	0.20
60R065X	1.01	0.88	0.77	0.65	0.53	0.47	0.41	0.35	0.26
60R075X	1.16	1.02	0.89	0.75	0.61	0.54	0.47	0.41	0.30
60R090X	1.40	1.22	1.07	0.90	0.73	0.65	0.57	0.49	0.36
60R110X	1.71	1.50	1.31	1.10	0.89	0.79	0.69	0.59	0.44
60R135X	2.09	1.84	1.61	1.35	1.09	0.97	0.85	0.73	0.54
60R160X	2.48	2.18	1.90	1.60	1.30	1.15	1.01	0.86	0.64
60R185X	2.87	2.52	2.20	1.85	1.50	1.33	1.17	1.00	0.74
60R250X	3.88	3.40	2.98	2.50	2.03	1.80	1.58	1.35	1.00
60R300X	4.65	4.08	3.57	3.00	2.43	2.16	1.89	1.62	1.20
60R375X	5.81	5.10	4.46	3.75	3.04	2.70	2.36	2.03	1.50

Average Time Current Curves



The average time current curves and Temperature Derating curve performance is affected by a number of variables, and these curves provided as guidance only. Customer must verify the performance in their application.

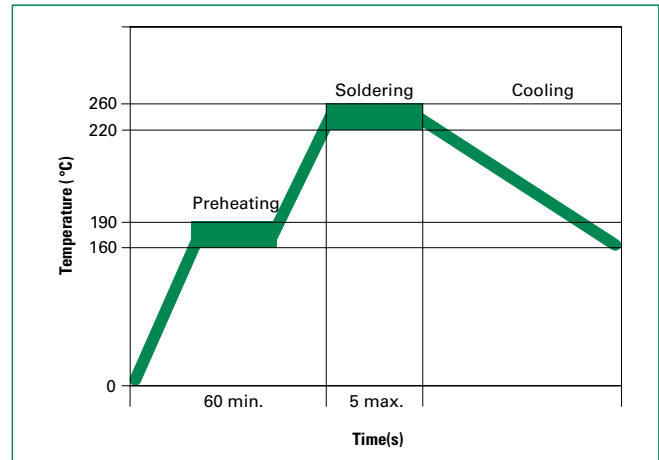
Temperature Derating Curve



Note:
Typical Temperature derating curve, refer to table for derating data

Soldering Parameters - Wave Soldering

Pre-Heating Zone	Refer to the condition recommended by the flux manufacturer. Max. ramping rate should not exceed 4°C/Sec.
Soldering Zone	Max. solder temperature should not exceed 260°C Time within 5°C of actual Max. solder temperature within 3 - 5 seconds Total time from 25°C room to Max. solder temperature within 5 minutes including Pre-Heating time
Cooling Zone	Cooling by natural convection in air. Max. ramping down rate should not exceed 6°C/Sec.



Physical Specifications

Lead Material	.20-.40A: Tin-plated Copper clad steel .50-3.75A: Tin-plated Copper
Soldering Characteristics	Solderability per MIL-STD-202, Method 208
Insulating Material	Cured, flame retardant epoxy polymer meets UL94V-0 requirements.
Device Labeling	Marked with 'LF', voltage, current rating, and date code.

Environmental Specifications

Operating/Storage Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85°C, 1000 hours -/+ 5% typical resistance change
Humidity Aging	+85°C, 85% R.H., 1000 hours -/+ 5% typical resistance change
Thermal Shock	+85°C to -40°C 10 times 30% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215
Moisture Resistance Level	Level 1, J-STD-020

Additional Information



Datasheet

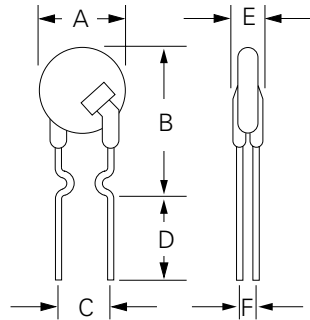


Resources

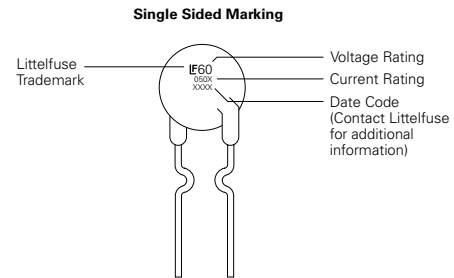


Samples

Dimensions

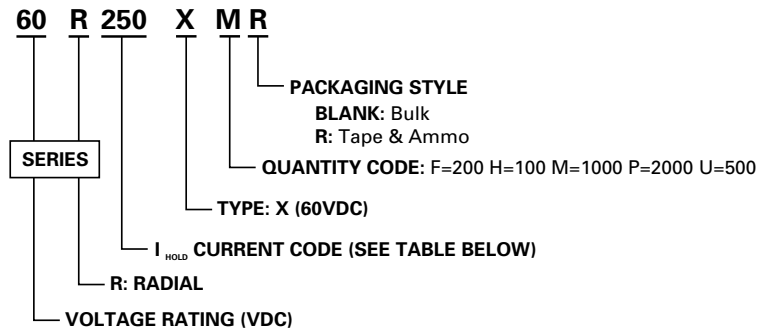


Part Marking System



Part Number	A		B		C		D		E		F		Physical Characteristics		
	Inches	mm	Inches	mm	Inches	mm	Inches	mm	Inches	mm	Inches	mm	Lead (dia)		Material
	Max.	Max.	Max.	Max.	Typ.	Typ.	Min.	Min.	Max.	Max.	Typ.	Typ.	Inches	mm	
60R010X	0.29	7.4	0.50	12.7	0.20	5.1	0.30	7.6	0.12	3.1	0.047	1.2	0.02	0.51	Sn/CuFe
60R017X	0.29	7.4	0.50	12.7	0.20	5.1	0.30	7.6	0.12	3.1	0.047	1.2	0.02	0.51	Sn/CuFe
60R020X	0.29	7.4	0.46	11.7	0.20	5.1	0.30	7.6	0.12	3.1	0.047	1.2	0.02	0.51	Sn/CuFe
60R025X	0.29	7.4	0.50	12.7	0.20	5.1	0.30	7.6	0.12	3.1	0.047	1.2	0.02	0.51	Sn/CuFe
60R030X	0.29	7.4	0.50	12.7	0.20	5.1	0.30	7.6	0.12	3.1	0.047	1.2	0.02	0.51	Sn/CuFe
60R040X	0.30	7.6	0.53	13.5	0.20	5.1	0.30	7.6	0.12	3.1	0.047	1.2	0.02	0.51	Sn/CuFe
60R050X	0.31	7.9	0.54	13.7	0.20	5.1	0.30	7.6	0.12	3.1	0.047	1.2	0.02	0.51	Sn/Cu
60R065X	0.37	9.4	0.57	14.5	0.20	5.1	0.30	7.6	0.12	3.1	0.047	1.2	0.02	0.51	Sn/Cu
60R075X	0.40	10.2	0.59	15	0.20	5.1	0.30	7.6	0.12	3.1	0.047	1.2	0.02	0.51	Sn/Cu
60R090X	0.44	11.2	0.62	15.8	0.20	5.1	0.30	7.6	0.12	3.1	0.047	1.2	0.02	0.51	Sn/Cu
60R110X	0.51	13	0.72	18.2	0.20	5.1	0.30	7.6	0.12	3.1	0.055	1.4	0.03	0.81	Sn/Cu
60R135X	0.53	13.58	0.78	19.8	0.20	5.1	0.30	7.6	0.12	3.1	0.055	1.4	0.03	0.81	Sn/Cu
60R160X	0.60	15.36	0.85	21.6	0.20	5.1	0.30	7.6	0.12	3.1	0.055	1.4	0.03	0.81	Sn/Cu
60R185X	0.66	16.76	0.91	23	0.20	5.1	0.30	7.6	0.12	3.1	0.055	1.4	0.03	0.81	Sn/Cu
60R250X	0.78	19.93	1.03	26.2	0.40	10.2	0.30	7.6	0.12	3.1	0.055	1.4	0.03	0.81	Sn/Cu
60R300X	0.91	23.11	1.15	29.3	0.40	10.2	0.30	7.6	0.12	3.1	0.055	1.4	0.03	0.81	Sn/Cu
60R375X	1.04	26.3	1.22	31.1	0.40	10.2	0.30	7.6	0.12	3.1	0.055	1.4	0.03	0.81	Sn/Cu

Part Ordering Number System



Packaging

Part Number	Ordering Number	I _{hold} (A)	I _{hold} Code	Packaging Option	Quantity	Quantity & Packaging Codes
60R010X	60R010XU	0.10	010	Bulk	500	U
	60R010XPR			Tape and Ammo	2000	PR
60R017X	60R017XU	0.20	020	Bulk	500	U
	60R017XPR			Tape and Ammo	2000	PR
60R020X	60R020XU	0.20	020	Bulk	500	U
	60R020XPR			Tape and Ammo	2000	PR
60R025X	60R025XU	0.25	025	Bulk	500	U
	60R025XPR			Tape and Ammo	2000	PR
60R030X	60R030XU	0.30	030	Bulk	500	U
	60R030XPR			Tape and Ammo	2000	PR
60R040X	60R040XU	0.40	040	Bulk	500	U
	60R040XPR			Tape and Ammo	2000	PR
60R050X	60R050XU	0.50	050	Bulk	500	U
	60R050XPR			Tape and Ammo	2000	PR
60R065X	60R065XU	0.65	065	Bulk	500	U
	60R065XPR			Tape and Ammo	2000	PR
60R075X	60R075XU	0.75	075	Bulk	500	U
	60R075XPR			Tape and Ammo	2000	PR
60R090X	60R090XU	0.90	090	Bulk	500	U
	60R090XPR			Tape and Ammo	2000	PR
60R110X	60R110XU	1.10	110	Bulk	500	U
	60R110XMR			Tape and Ammo	1000	MR
60R135X	60R135XF	1.35	135	Bulk	200	F
	60R135XMR			Tape and Ammo	1000	MR
60R160X	60R160XF	1.60	160	Bulk	200	F
	60R160XMR			Tape and Ammo	1000	MR
60R185X	60R185XF	1.85	185	Bulk	200	F
	60R185XMR			Tape and Ammo	1000	MR
60R250X	60R250XF	2.50	250	Bulk	200	F
	60R250XMR			Tape and Ammo	1000	MR
60R300X	60R300XF	3.00	300	Bulk	200	F
60R375X	60R375XH	3.75	375	Bulk	100	H

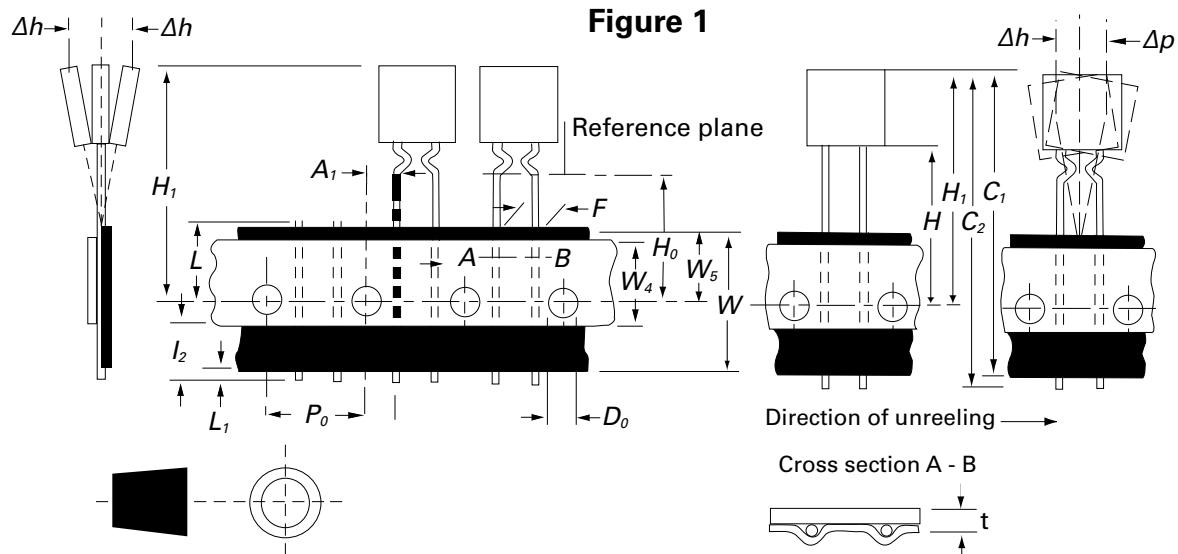
Tape and Ammo Specifications

Devices taped using EIA468-B/IE286-2 standards. See table below and Figure 1 for details.

Dimension	EIA Mark	IEC Mark	Dimensions	
			Dim. (mm)	Tol. (mm)
Carrier tape width	W	W	18	-0.5 / +1.0
Hold down tape width	W ₄	W ₀	11	min.
Top distance between tape edges	W ₆	W ₂	3	max.
Sprocket hole position	W ₅	W ₁	9	-0.5 / +0.75
Sprocket hole diameter*	D ₀	D ₀	4	-0.32 / +0.2
Abscissa to plane(straight lead)	H	H	18.5	-/+ 3.0
Abscissa to plane(kinked lead)	H ₀	H ₀	16	-/+ 0.5
Abscissa to top 60R010-60R090	H ₁	H ₁	32.2	max.
Abscissa to top 60R110-60R300	H ₁	-	47.5	max.
Overall width without lead protrusion:60R010-60R090	C ₁	-	42.5	max.
Overall width without lead protrusion:60R110-60R300	-	-	57	-
Overall width with lead protrusion:60R010-60R090	C2	-	43.2	max.
Overall width with lead protrusion:60R110-60R300	-	-	58	-
Lead protrusion	L ₁	L ₁	1.0	max.
Protrusion of cut out	L	L	11	max.
Protrusion beyond hold-down tape	L ₂	L ₂	Not specified	-
Sprocket hole pitch:60R010-60R090	P ₀	P ₀	12.7	-/+ 0.3
Sprocket hole pitch:60R110-60R300	P ₀	P ₀	25.4	-/+ 0.5
Pitch tolerance	-	-	20 consecutive.	-/+ 1
Device pitch:60R010-60R090	-	-	12.7	-
Device pitch:60R110-60R300	-	-	25.4	-
Tape thickness	t	t	0.9	max.
Tape thickness with splice	t ₁	-	2.0	max.
Splice sprocket hole alignment	-	-	0	-/+ 0.3
Body lateral deviation	Δh	Δh	0	-/+ 1.0
Body tape plane deviation	Δp	Δp	0	-/+ 1.3
Ordinate to adjacent component lead*:60R010-60R090	P ₁	P ₁	3.81	-/+ 0.7
Ordinate to adjacent component lead*:60R110-60R300	-	-	7.62	-/+ 0.7
Lead spacing:60R010-60R185	F	F	5.08	-/+ 0.8
Lead spacing:60R250-60R300	F	F	10.18	-/+ 0.8

*Differs from EIA Specification

Tape and Ammo Diagram



WARNING

- Users shall independently assess the suitability of these devices for each of their applications
- Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire
- These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration
- Exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials can adversely affect the performance of these PPTC devices
- These devices undergo thermal expansion under fault conditions, and thus shall be provided with adequate space and be protected against mechanical stresses
- Circuits with inductance may generate a voltage ($L \, di/dt$) above the rated voltage of the PPTC device.

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